

AMENDMENTS TO THE CLAIMS

1. (Currently Amended) A circuit board, comprising:
a base layer;
a first conductive ~~circuit~~ circuit, manufactured by hardening a conductive paste material formed in a predetermined shape on said base layer;
a first insulating ~~layer~~ layer, manufactured by hardening an insulating paste material formed on said base layer ~~including~~ and said first conductive circuit; and
a second conductive ~~circuit~~ circuit, manufactured by hardening a conductive paste material formed in a predetermined shape on said first insulating layer.

2. (Currently Amended) The circuit board ~~of~~ according to claim 1, wherein ~~wherein~~ said first insulating layer is ~~formed~~ only on a part of said base layer.

3. (Currently Amended) The circuit board ~~of~~ according to claim 1, wherein ~~wherein~~ said base layer ~~is~~ comprises a film member.

4. (Currently Amended) The circuit board ~~of~~ according to claim 3, further comprising: ~~further comprising~~ a plate member ~~which is fitted to~~ on a part of the a ~~opposite~~ surface of said base layer that is opposite to a surface of said base layer on which ~~where~~ said first conductive circuit is formed.

5. (Currently Amended) The circuit board ~~of~~ according to claim 1, wherein ~~wherein~~ said base layer ~~is~~ comprises a plate member.

6. (Currently Amended) The circuit board ~~of~~ according to claim 5, further comprising: ~~further comprising~~ another plate member,

wherein at least said first insulating layer is ~~indirectly held~~ positioned between said base layer and said another plate member.

7. (Currently Amended) The circuit board ~~of~~ according to claim 1, further comprising:
~~wherein~~ a connection opening ~~is formed~~ in said first insulating layer ~~formed~~ on said first conductive circuit, ~~and said first conductive circuit and said second conductive circuit are electrically connected with each other via said connection opening.~~

wherein said first conductive circuit and said second conductive circuit are electrically connected to each other via said connection opening.

8. (Currently Amended) The circuit board ~~of~~ according to claim 1, further comprising:
~~further comprising~~ a resistance ~~layer~~ layer, formed by hardening a resistance paste material coated ~~on~~ onto one of said base layer ~~or~~ and said first insulating layer,

wherein said resistance layer forms a resistor electrically connected to one of said first conductive circuit ~~or~~ and said second conductive circuit.

9. (Currently Amended) The circuit board ~~of~~ according to claim 1, further comprising:
~~further comprising~~ a resistance ~~layer~~ layer, formed by hardening a resistance paste material applied to a resistance opening ~~formed~~ in said first insulating layer,

wherein said resistance layer forms a resistor electrically connected to said first conductive circuit and said second conductive circuit.

10. (Currently Amended) The circuit board ~~of~~ according to claim 1, further comprising:
~~further comprising~~ a dielectric ~~layer~~ layer, formed by hardening a dielectric paste material coated ~~on~~ onto one of said base layer ~~or~~ and said first insulating layer,

wherein said dielectric layer forms a capacitor electrically connected to one of said first conductive circuit ~~or~~ and said second conductive circuit.

11. (Currently Amended) The circuit board ~~of~~ according to claim 1, further comprising:
~~further comprising~~ a dielectric ~~layer~~ layer, formed by hardening a dielectric paste material applied to a dielectric opening ~~formed~~ in said first insulating layer,
wherein said dielectric layer forms a capacitor electrically connected to said first conductive circuit and said second conductive circuit.

12. (Currently Amended) The circuit board ~~of~~ according to claim 1, wherein
~~wherein~~ a part of one of said first conductive circuit ~~or~~ and said second conductive circuit forms an inductor.

13. (Currently Amended) The circuit board ~~of~~ according to claim 1, wherein
~~wherein~~ one of said first conductive circuit ~~or~~ and said second conductive circuit is connected to metallic wiring formed by any one of a depositing, plating and sputtering ~~processes~~ process.

14. (Currently Amended) The circuit board ~~of~~ according to claim 13, wherein
~~wherein~~ said metallic wiring is connected to an electrode ~~terminals~~ terminal of a bare chip IC.

15. (Currently Amended) The circuit board ~~of~~ according to claim 1, further comprising:
~~further comprising~~ electronic parts mounted on said second conductive circuit.

16. (Currently Amended) A method of manufacturing a circuit board, comprising ~~the~~
~~steps of~~:

a) forming a first conductive circuit by hardening a conductive paste material formed in a predetermined shape on a base layer;

b) forming a first insulating layer by hardening an insulating paste material coated ~~on~~ onto said base layer ~~including~~ and said first conductive circuit; and

c) forming a second conductive circuit by hardening a conductive paste material formed in a predetermined shape on said first insulating layer.

17. (Currently Amended) The method of manufacturing a circuit board ~~of~~ according to claim 16, wherein

~~wherein forming a first insulating layer comprises forming a first insulating layer having a connection opening is formed in that portion of said first insulating layer that is on said first conductive circuit in the step b), and~~

forming a second conductive circuit comprises filling said conductive paste material into said connection opening such that said first conductive circuit and said second conductive circuit are connected with interconnected by said conductive paste material filled applied to into said connection opening in the step c).

18. (Currently Amended) The method of manufacturing a circuit board ~~of~~ according to claim 16, further comprising:

~~further comprising a step of forming a resistive resistive layer by hardening a resistance paste material coated on onto one of said base layer or and said first insulating layer in the step a) or c); layer,~~

wherein such that a resistor electrically connecting said first conductive circuit to said second conductive circuit is formed.

19. (Currently Amended) The method of manufacturing a circuit board ~~of~~ according to claim 16, further comprising:

~~further comprising the steps of forming a resistance opening in said first insulating layer on said first conductive circuit in the step b), and layer; and~~

forming a resistive resistive layer by hardening a resistance paste material applied to said resistance opening in the step c),

~~wherein~~ such that a resistor electrically connected to said first conductive circuit and said second conductive circuit is formed.

20. (Currently Amended) The method of manufacturing a circuit board ~~of~~ according to claim 16, further comprising:

~~further comprising a step of~~ forming a dielectric layer by hardening a dielectric paste material coated ~~on~~ onto one of said base layer ~~or~~ and said first insulating layer ~~in the step a) or c),~~

~~wherein~~ such that a capacitor electrically connecting said first conductive circuit to said second conductive circuit is formed.

21. (Currently Amended) The method of manufacturing a circuit board ~~of~~ according to claim 16, further comprising:

~~further comprising the steps of~~ forming a dielectric opening in said first insulating layer on said first conductive ~~circuit in the step b), and~~ circuit; and

forming a dielectric layer by hardening a dielectric paste material applied to said dielectric opening ~~in the step c),~~

~~wherein~~ such that a capacitor electrically connected to said first conductive circuit and said second conductive circuit is formed.

22. (Currently Amended) The method of manufacturing a circuit board ~~of~~ according to claim 16, further comprising:

~~wherein~~ forming an inductor ~~is formed~~ on a part of one of said first conductive circuit ~~or~~ and said second conductive circuit ~~in the step a) or c).~~

23. (Currently Amended) A circuit board, comprising:

a part arrangement layer with an electronic ~~parts~~ part disposed in such a manner that an electrode ~~terminals~~ terminal of said electronic ~~parts~~ part ~~having the electrode terminals are~~ part is exposed on one surface ~~thereof,~~ of said electronic part; and

a second conductive circuit formed in a predetermined shape, said second ~~which is~~
conductive circuit being electrically connected to said electrode ~~terminals on said part~~
~~arrangement layer~~ terminal;

wherein said part arrangement layer ~~comprises~~ includes

(i) ~~a first conductive circuit~~ circuit, formed by hardening a conductive paste material
coated in a predetermined shape, and

(ii) ~~an insulating layer~~ layer, formed by hardening an insulating paste material coated ~~on~~
onto said first conductive circuit, ~~and is~~ said insulating layer being formed in such a manner that
said electrode ~~terminals of said electronic parts are~~ terminal is exposed on ~~the~~ a surface of said
insulating layer.

24. (Currently Amended) The circuit board ~~of~~ according to claim 23, further comprising:
~~wherein there is provided~~ a connection opening in said insulating layer on said first
conductive circuit, and said first conductive circuit ~~and said second conductive circuit are~~
~~electrically connected with each other via said connection opening~~.

wherein said first conductive circuit and said second conductive circuit are electrically
connected with each other via said connection opening.

25. (Currently Amended) The circuit board of claim 23, wherein
~~wherein~~ said part arrangement layer further includes other electronic parts electrically
connected to said first conductive circuit.

26. (Currently Amended) The circuit board of claim 23, further comprising:
~~further comprising~~ a base layer which ~~holds~~ supports said part arrangement layer, said
base layer being adhered via an adhesive to ~~being in tight contact with the~~ a surface of said
electronic part that is opposite surface of the to said one surface of said electronic part ~~where said~~
~~electrode terminals of said electronic parts are formed~~,
~~wherein said electronic parts are bonded to said base layer by using adhesive~~.

27. (Currently Amended) The circuit board of claim 26, wherein
~~wherein~~ said part arrangement layer is ~~formed~~ only on a part of said base layer.
28. (Currently Amended) The circuit board of claim 26, wherein
~~wherein~~ said base layer is comprises a film member.
29. (Currently Amended) The circuit board of claim 28, further comprising:
~~further comprising~~ a plate member ~~fitted~~ connected to a part of ~~the~~ a surface of said part
arrangement layer that is opposite to a surface of said part arrangement layer of that is connected
to said base layer.
30. (Currently Amended) The circuit board of claim 26, wherein
~~wherein~~ said base layer is comprises a plate member.
31. (Currently Amended) The circuit board of claim 30, further comprising:
~~further comprising~~ another plate member,
wherein said part arrangement layer is sandwiched between said base layer and said
another plate member.
32. (Currently Amended) The circuit board of claim 23, wherein
~~wherein~~ one of said first conductive circuit ~~or~~ and said second conductive circuit is
connected to metallic wiring formed by any one of a depositing, plating and sputtering ~~processes~~
process.
33. (Currently Amended) The circuit board of claim 32, wherein
~~wherein~~ said electronic part is comprises a semiconductor integrated circuit element of
bare chip configuration, and

said metallic wiring is formed so as to connect ~~the~~ an electrode terminals terminal of said semiconductor integrated circuit element ~~in said part arrangement layer~~ to said second conductive circuit.

34. (Currently Amended) The circuit board of claim 23, wherein ~~wherein~~ said part arrangement layer is further ~~mounted~~ provided with other electronic parts.

35. (Currently Amended) A method of manufacturing a circuit board, comprising the steps of:

- a) forming a part arrangement layer having a part opening,
wherein ~~the step of forming said part arrangement layer includes~~ comprises the steps of:
 - a1) (i) forming a first conductive circuit by hardening a conductive paste material formed in a predetermined ~~shape;~~ shape,
 - a2) (ii) forming a first insulating layer by hardening an insulating paste ~~material~~ material, coated in a shape having defining said part opening opening, on a predetermined portion of a surface including said first conductive ~~circuit;~~ circuit,
 - a3) (iii) inserting an electronic part into said part opening in such a manner that an electrode ~~terminals terminal~~ is exposed; exposed, and
 - a4) (iv) forming a second insulating layer by hardening an insulating paste material coated ~~on~~ onto said electronic part and said first insulating layer in such a manner that at least a surface of said electrode ~~terminals terminal~~ surface of said electronic part is ~~exposed;~~ exposed; and
- b) forming a second conductive circuit in a predetermined shape on said first part arrangement layer including and said electrode ~~terminals terminal~~ of said electronic part.

36. (Currently Amended) The method of manufacturing a circuit board ~~of~~ according to claim 35, wherein

forming a second conductive circuit comprises ~~wherein said second conductive circuit is formed by~~ hardening a conductive paste coated ~~in the step b)~~ onto said first part arrangement layer and said electrode terminal.

37. (Currently Amended) The method of manufacturing a circuit board ~~of~~ according to claim 36, wherein

wherein forming a first insulating layer comprises forming a first insulating layer having a connection opening ~~is formed in a portion of said first insulating layer that is on in a predetermined position of said first conductive circuit in the step a2), and~~

forming a second conductive circuit comprises filling said conductive paste into said connection opening such that said first conductive circuit and said second conductive circuit are electrically ~~connected with each other by~~ interconnected by hardening ~~the~~ said conductive paste material also applied to ~~said connection opening in the step b).~~

38. (Currently Amended) The method of manufacturing a circuit board ~~of~~ according to claim 35, further comprising:

~~further comprising the steps of making~~ forming a second part opening that ~~goes~~ extends through said part arrangement layer and said second conductive ~~circuit;~~ circuit; and ~~inserting a second electronic part thicker than the first electronic part into said second part opening.~~

inserting a second electronic part, that is thicker than said first electronic part, into said second part opening.

39. (Currently Amended) The method of manufacturing a circuit board ~~of~~ according to claim 35, wherein

wherein forming a part arrangement layer comprises forming said part arrangement layer is formed on a film base layer, and further comprising:

securing said electronic part is inserted and secured in within said part opening ~~with~~ via adhesive applied ~~thereto in the step 3a).~~